15. The method of claim 1, wherein the insulator comprises aluminum oxide and the conductive elements comprise a cermet.

16. The method of claim 1, wherein depositing the metal or metal alloy includes depositing the metal or metal alloy with a thickness in a range from 200 µm to 800 µm.

17. A method of forming a feedthrough device for an implantable medical device, the method comprising:

providing an insulator having one or more conducting elements extending therethrough, the insulator having a perimeter edge surface;

metallizing the perimeter edge surface to provide a metallized layer thereon; and

depositing one of a metal, metal alloy, or cermet having a thickness in a range from 200 to 800 µm on the metallized layer using a powder deposition process to form a ferrule thereon and thereby form the feedthrough device.

18. The method of claim 17, wherein the metallized layer has a thickness in a range from 0.2 µm to 10 µm and comprises a metal selected from a group of metals consisting of titanium, niobium, platinum,~~. Palladium~~palladium~~,~~ and gold.

19. The method of claim 17, wherein the powder deposition process comprises a Laser Engineered Net Shaping™ process.

20. The method of claim 17, wherein the powder deposition process comprises a plasma thermal spraying process.

~~21. A feedthrough for a medical implantable device comprising:~~

~~a ferrule comprising a metal that is configured to be welded to a case of the implantable device;~~

~~an insulator substantially surrounded by the ferrule and sharing an interface therewith, the insulator comprising a glass or ceramic material;~~

~~conductive elements formed through the insulator providing an electrically conductive path through the insulator;~~

~~characterized in that there is no braze, solder, or weld joint at the interface between the ferrule and the insulator and that there is no braze or solder at interfaces between the insulator and the conductive elements.~~